

ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number: BCW60D,215
Manufacturer: Nexperia USA Inc.
Package: TO-236-3, SC-59, SOT-23-3
Availability: Please confirm with sales

Product Page:

<https://antrexco.com/product/details/nexperia-usa-inc/bcw60d-215.html>

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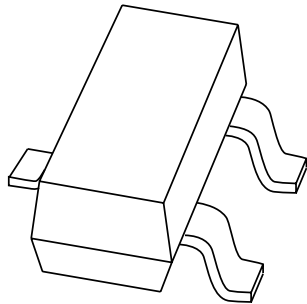
Secure sourcing support for OEM / EMS projects

Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

DATA SHEET



BCW60 series NPN general purpose transistors

Product data sheet
Supersedes data of 1997 Mar 10

1999 Apr 22

NPN general purpose transistors

BCW60 series

FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 32 V).

APPLICATIONS

- General purpose switching and amplification.

DESCRIPTION

NPN transistor in a SOT23 plastic package.
PNP complements: BCW61 series.

MARKING

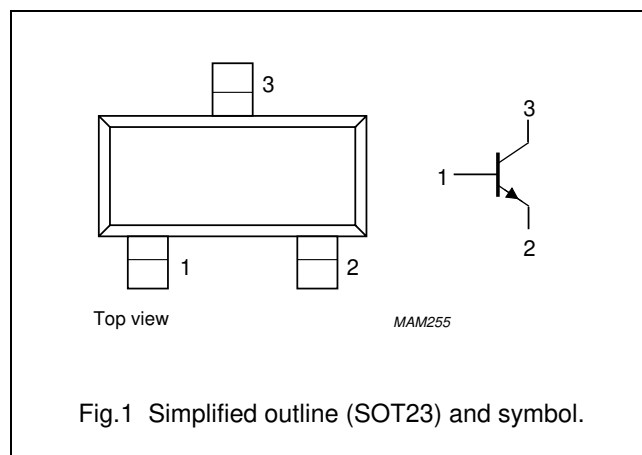
TYPE NUMBER	MARKING CODE ⁽¹⁾
BCW60B	AB*
BCW60C	AC*
BCW60D	AD*

Note

1. * = p : Made in Hong Kong.
* = t : Made in Malaysia.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	32	V
V_{CEO}	collector-emitter voltage	open base	–	32	V
V_{EBO}	emitter-base voltage	open collector	–	5	V
I_C	collector current (DC)		–	100	mA
I_{CM}	peak collector current		–	200	mA
I_{BM}	peak base current		–	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	–	250	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

NPN general purpose transistors

BCW60 series

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{CBO}	collector cut-off current	$I_E = 0; V_{CB} = 32\text{ V}$	–	–	20	nA
		$I_E = 0; V_{CB} = 32\text{ V}; T_{amb} = 150\text{ }^{\circ}\text{C}$	–	–	20	μA
I_{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = 4\text{ V}$	–	–	20	nA
h_{FE}	DC current gain	$I_C = 10\text{ }\mu\text{A}; V_{CE} = 5\text{ V}$				
	BCW60B		20	–	–	
	BCW60C		40	–	–	
	BCW60D		100	–	–	
	DC current gain	$I_C = 2\text{ mA}; V_{CE} = 5\text{ V}$				
	BCW60B		180	–	310	
	BCW60C		250	–	460	
	BCW60D		380	–	630	
	DC current gain	$I_C = 50\text{ mA}; V_{CE} = 1\text{ V}$				
	BCW60B		70	–	–	
	BCW60C		90	–	–	
	BCW60D		100	–	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.25\text{ mA}$	50	–	350	mV
		$I_C = 50\text{ mA}; I_B = 1.25\text{ mA}$	100	–	550	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.25\text{ mA}$	600	–	850	mV
		$I_C = 50\text{ mA}; I_B = 1.25\text{ mA}$	0.7	–	1.05	V
V_{BE}	base-emitter voltage	$I_C = 10\text{ }\mu\text{A}; V_{CE} = 5\text{ V}$	–	520	–	mV
		$I_C = 2\text{ mA}; V_{CE} = 5\text{ V}$	550	650	750	mV
		$I_C = 50\text{ mA}; V_{CE} = 1\text{ V}$	–	780	–	mV
C_c	collector capacitance	$I_E = I_C = 0; V_{CB} = 10\text{ V}; f = 1\text{ MHz}$	–	1.7	–	pF
C_e	emitter capacitance	$I_C = I_E = 0; V_{EB} = 0.5\text{ V}; f = 1\text{ MHz}$	–	11	–	pF
f_T	transition frequency	$I_C = 10\text{ mA}; V_{CE} = 5\text{ V}; f = 100\text{ MHz}; \text{note 1}$	100	250	–	MHz
F	noise figure	$I_C = 200\text{ }\mu\text{A}; V_{CE} = 5\text{ V}; R_S = 2\text{ k}\Omega; f = 1\text{ kHz}; B = 200\text{ Hz}$	–	2	6	dB

Note

1. Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

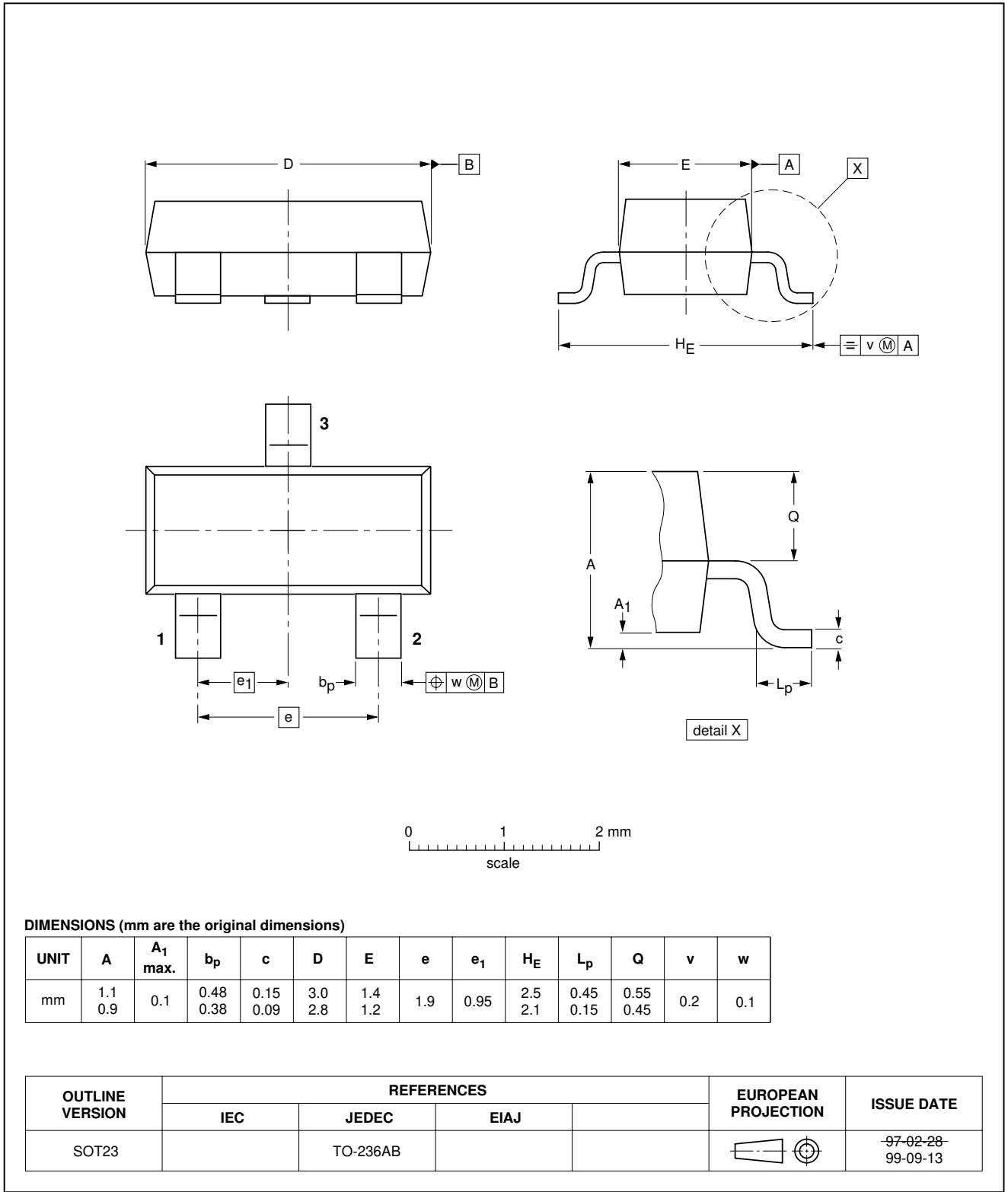
NPN general purpose transistors

BCW60 series

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT23



NPN general purpose transistors

BCW60 series

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

1. Please consult the most recently issued document before initiating or completing a design.
2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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